Amendments to the Claims

Please cancel claims 11, 14, and 16 without prejudice.

This listing of claims will replace all prior versions, and listings, of claims in the above-captioned application:

Listing of the Claims:

1. (Currently amended): A process for producing a printed wiring board, which ~~comprises~~ comprises: gluing a prepreg to a metal foil surface and hot pressing the prepeg and the metal foil surface to produce a laminate board, and forming a circuit on an outer layer of the laminate board to yield a printed wiring board; wherein said prepreg is manufactured by impregnating a reinforcing material with~~using~~ an epoxy resin composition ~~in producing a printed wiring board~~followed by drying and semi-curing the composition to B-stage; said epoxy resin composition comprising an epoxy resin, a phenol novolac resin, a curing accelerator and a silica filler; wherein said silica filler is a silica filler which has a shape having at least two planes, and has an average particle diameter between 0.3 μm and 10 μm and a relative surface area between 8 m^2/g and 30 m^2/g.

2. (Previously presented): A process for producing a printed wiring board as described in claim 1, wherein said silica filler is a silica filler having at least two planes in the shape, an average particle diameter between 0.3 μm and 10 μm and a relative surface area between 10 m^2/g and 20 m^2/g.

3. (Previously presented): A process for producing a printed wiring board as described in claim 1, wherein said silica filler is added in an amount of from 3% to 80% by weight per the solid content of the resin.

4. (Previously presented): A process for producing a printed wiring board as described in claim 1, wherein said silica filler is a silica filler having an electric conductivity of 15 μs or less.

5. (Previously presented): A process for producing a printed wiring board as described in claim 1, wherein said silica filler is a silica filler which has been vitrified through melting at a temperature of 1800°C or higher.

6. (Previously presented): A process for producing a printed wiring board as described in claim 1, wherein said epoxy resin is an epoxy resin having a bromine content of between 5% and 20% by weight per the solid content of the resin without silica filler and containing an epoxy resin obtained by reacting a dihydric phenol with a bisphenol A type epoxy resin in an amount of between 40% and 100% by weight based on the whole amount of the epoxy resin solid content.

7. (Previously presented): A process for producing a printed wiring board as described in claim 1, wherein said epoxy resin is an epoxy resin having a bromine content of between 5% and 20% by weight per the solid content of the resin without silica filler and containing an epoxy resin possessing a dicyclopentadienyl structure in an amount of between 40% and 100% by weight based on the whole amount of the epoxy resin solid content.

8. (Previously presented): A process for producing a printed wiring board as described in claim 1, wherein said epoxy resin is an epoxy resin having a bromine content of between 5% and 20% by weight per the solid content of the resin without silica filler and containing of a novolac type

epoxy resin in an amount of between 40% and 100% by weight based on the whole amount of the epoxy resin solid content.

9. (Previously presented): A process for producing a printed wiring board as described in claim 1, wherein said epoxy resin composition is a bromine-free epoxy resin composition.

10. (Previously presented): A process for producing a printed wiring board, which ~~comprises~~comprises: ~~using~~ coupling a prepreg to a metal foil surface to produce a laminate board, and forming a circuit on an outer layer of the laminate board to yield ~~in producing~~ a printed wiring board; wherein said prepreg is obtained by impregnating a reinforcing material with an epoxy resin composition for a printed wiring board and drying said composition to B-stage; said epoxy resin composition comprising an epoxy resin, a phenol novolac resin, a curing accelerator, and a silica filler which has a shape having at least two planes and has an average particle diameter between 0.3 μm and 10 μm and a relative surface area between 8 m^2/g and 30 m^2/g.

11. (Canceled)

12. (Previously presented): A printed wiring board, which is ~~obtained by using~~ formed from a laminated board ~~for a printed wiring board~~; wherein said laminate board is obtained by ~~gluing a prepreg as described in claim 10 to a surface of a metal foil and hot pressing them~~ coupling a prepreg to a metal foil surface to produce a laminate board, and forming a circuit on an outer layer of the laminate board to yield a printed wiring board; wherein said prepreg is obtained by impregnating a reinforcing material with an epoxy resin composition for a printed wiring board and drying said composition to B-stage; said epoxy resin composition comprising an epoxy resin, a phenol novolac resin, a curing accelerator, and a silica filler which has a shape

having at least two planes and has an average particle diameter between 0.3 μm and 10 μm and a relative surface area between 8 m^2/g and 30 m^2/g.

13. (Previously presented): A process for producing a printed wiring board as described in claim 1, which comprises ~~the following steps~~:

(1) preparing a prepreg for a printed wiring board, by preparing a varnish of said epoxy resin composition with an organic solvent, impregnating the varnish into a glass cloth, and drying it in an oven to make it into a semi-cured state (B-stage);

(2) manufacturing a laminated board for a printed wiring board by stacking a prescribed number of sheets of said prepreg and hot-pressing them through laminate molding, and placing a metal foil on one or both sides of the prescribed number of the prepreg sheets stacked for printed wiring board and laminate-molded to yield a metal foil-clad laminated board; and

(3) forming a circuit on an outer layer of the laminated board for printed wiring board to yield a printed wiring board.

14. (Canceled)

15. (Previously presented): A printed wiring board, which is obtained by the process as described in claim 13.

16. (Canceled)